

Silicon Carbide Power MOSFET C3M™ MOSFET Technology N-Channel Enhancement Mode

Features

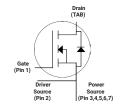
- 3rd generation SiC MOSFET technology
- Optimized package with separate driver source pin
- High blocking voltage with low on-resistance
- High-speed switching with low capacitances
- Fast intrinsic diode with low reverse recovery (Q_{rr})
- Halogen free, RoHS compliant







TO-263-7L XL



Package Types: TO-263-7L XL PN's: C3M0025065J1

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Typical Applications

- Datacenter and telecom power supplies
- EV battery chargers
- High voltage DC/DC converters
- Energy storage systems
- Solar inverters

Benefits

- Reduce switching losses and minimize gate ringing
- Higher system efficiency
- Reduce cooling requirements
- Increase power density
- Increase system switching frequency

Key Parameters

Parameter	Symbol	Min.	Тур.	Max	Unit	Conditions	Note
Drain - Source Voltage	V _{DS}			650		T _c = 25°C	
Maximum Gate - Source Voltage	V _{GS(max)}	-8		+19	v	Transient	
Operational Gate-Source Voltage	V _{GS op}		-4/15			Static	Note 1
DC Continuous Drain Current	I _D			80	A	V _{GS} = 15 V, T _C = 25 °C, T _J ≤150 °C	Fig. 19 Note 2
DC Continuous Drain Current				59		$V_{GS} = 15 \text{ V}, T_{C} = 100 \text{ °C}, T_{J} \le 150 \text{ °C}$	
Pulsed Drain Current	I _{DM}			251		t_{Pmax} limited by T_{jmax} $V_{GS} = 15V$, $T_C = 25$ °C	Fig. 22
Power Dissipation	P _D			271	W	$T_{c} = 25 ^{\circ} \text{C}, T_{J} = 150 ^{\circ} \text{C}$	Fig. 20
Operating Junction Temperature	T,			-40 to +175			
Case and Storage Temperature	T_{c},T_{stg}			-40 to 150	°C		
Solder Temperature	T _L			260		According to JEDEC J-STD-020	

 $Note~(1): Recommended~turn-on~gate~voltage~is~15V~with~\pm5\%~regulation~tolerance, see~Application~Note~PRD-04814~for~additional~details~tolerance, see~Application~details~tolerance, see~Applicati$

Note (2): Verified by design

Electrical Characteristics ($T_c = 25$ °C Unless Otherwise Specified)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Test Conditions	Note
		1.8	2.3	3.6	V	$V_{DS} = V_{GS}, I_{D} = 9.22 \text{ mA}$	Fig. 11
Gate Threshold Voltage	V _{GS(th)}		2.0			$V_{DS} = V_{GS}$, $I_D = 9.22$ mA, $T_J = 150$ °C	
Zero Gate Voltage Drain Current	I _{DSS}		1	50	μΑ	$V_{DS} = 650 \text{ V}, V_{GS} = 0 \text{ V}$	
Gate-Source Leakage Current	I _{GSS}		10	250	nA	$V_{GS} = 15 \text{ V}, V_{DS} = 0 \text{ V}$	
	R _{DS(on)}		25	34		$V_{GS} = 15 \text{ V}, I_D = 33.5 \text{ A}$	Fig. 4,
Drain-Source On-State Resistance			30		mΩ	$V_{GS} = 15 \text{ V}, I_D = 33.5 \text{ A}, T_J = 150 ^{\circ}\text{C}$	5,6
			25		- S	$V_{DS} = 20 \text{ V}, I_{DS} = 33.5 \text{ A}$	Fig. 7
Transconductance	g fs		24			V _{DS} = 20 V, I _{DS} = 33.5 A, T _J = 150 °C	
Input Capacitance	C _{iss}		2980			V = 0 V V = 0 V to 400 V	Fig. 17, 18
Output Capacitance	C _{oss}		178			$V_{GS} = 0 \text{ V}, V_{DS} = 0 \text{ V to } 400 \text{ V}$ F = 1 Mhz	
Reverse Transfer Capacitance	C _{rss}		12		pF	V _{AC} = 25 mV	
Effective Output Capacitance (Energy Related)	C _{o(er)}		236		, pi	V = 0 V V = 0 V += 400 V	Note: 3
Effective Output Capacitance (Time Related)	C _{o(tr)}		340			$V_{GS} = 0 \text{ V}, V_{DS} = 0 \text{ V to } 400 \text{ V}$	Note: 3
C _{oss} Stored Energy	E _{oss}		19		μJ	V _{DS} = 400 V, F = 1 Mhz	Fig. 16
Turn-On Switching Energy (Body Diode)	E _{on}		116			$V_{DS} = 400 \text{ V}, V_{GS} = -4 \text{ V}/15 \text{ V}, I_D = 33.5 \text{ A},$	Fig. 25
Turn-Off Switching Energy (Body Diode)	E _{OFF}		59		μJ	$R_{G(ext)} = 2.5 \Omega$, L = 59 μ H, $T_J = 25 ^{\circ}$ C FWD = Internal Body Diode of MOSFET	
Turn-On Delay Time	t _{d(on)}		13				
Rise Time	t _r		20			$V_{DD} = 400 \text{ V}, V_{GS} = -4 \text{ V}/15 \text{ V}$ $I_D = 33.5 \text{ A}, R_{G(ext)} = 2.5 \Omega, L = 59 \mu\text{H}$	
Turn-Off Delay Time	t _{d(off)}		25		ns	Timing Relative to V _{DS} Inductive Load	Fig. 26
Fall Time	t _f		9			inductive Load	
Internal Gate Resistance	R _{G(int)}		1.3		Ω	F = 1 Mhz, V _{AC} = 25 mV	
Gate to Source Charge	$Q_{\rm gs}$		35			V - 400 V V - 4 V/15 V	Fig. 12
Gate to Drain Charge	$Q_{\rm gd}$		31		nC	$V_{DS} = 400 \text{ V}, V_{GS} = -4 \text{ V}/15 \text{ V}$ $I_D = 33.5 \text{ A}$	
Total Gate Charge	Q_{g}		109			Per IEC60747-8-4 pg 21	

Note (3): $C_{o(et)}$, a lumped capacitance that gives same stored energy as coss while V_{DS} is rising from 0 to 400 V. $C_{o(tt)}$, a lumped capacitance that gives same charging time as coss while V_{DS} is rising from 0 to 400 V.

Reverse Diode Characteristics ($T_c = 25$ °C Unless Otherwise Specified)

Parameter	Symbol	Тур.	Max.	Unit	Test Conditions	Note
Diode Forward Voltage	V	5.0		V	$V_{GS} = -4 \text{ V}, I_{SD} = 16.8 \text{ A}, T_{J} = 25 \text{ °C}$	Fig. 8, 9, 10
	V _{SD}	4.5		$V_{GS} = -4 \text{ V}, I_{SD} = 16.8 \text{ A}, T_{J} = 150 \text{ °C}$	1 ig. 0, 3, 10	
Continuous Diode Forward Current	I _s		45		V _{GS} = -4 V, T _C = 25 °C	
Diode Pulse Current	I _{S, pulse}		251	A	V_{GS} = -4 V, Pulse Width t_p Limited by T_{jmax}	
Reverse Recovery Time	t _{rr}	13		ns		
Reverse Recovery Charge	Q _{rr}	274		nC	$V_{GS} = -4 \text{ V}, I_{SD} = 33.5 \text{ A}, V_{R} = 400 \text{ V}$ $dif/dt = 5665 \text{ A}/\mu\text{s}, T_{J} = 25 \text{ °C}$	
Peak Reverse Recovery Current	I _{rrm}	37		A		
Reverse Recovery Time	t _{rr}	16		ns		
Reverse Recovery Charge	Q _{rr}	164		nC	$V_{GS} = -4 \text{ V}, I_{SD} = 33.5 \text{ A}, V_{R} = 400 \text{ V}$ $dif/dt = 1630 \text{ A/}\mu\text{s}, T_{J} = 25 \text{ °C}$	
Peak Reverse Recovery Current	I _{rrm}	17		А		

Thermal Characteristics

Parameter	Symbol	Тур.	Unit	Test Conditions	Note
Thermal Resistance from Junction to Case	$R_{\theta JC}$	0.46	96/14		F' 04
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	40	°C/W		Fig. 21

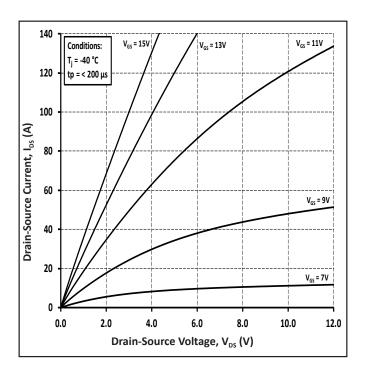


Figure 1. Output Characteristics $T_J = -40 \, ^{\circ}\text{C}$

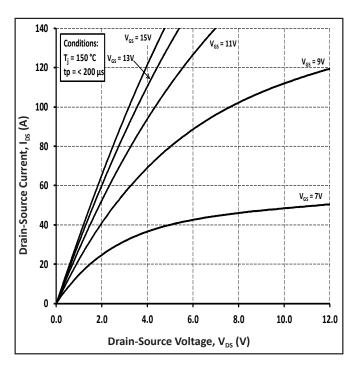


Figure 3. Output Characteristics T_J = 150 °C

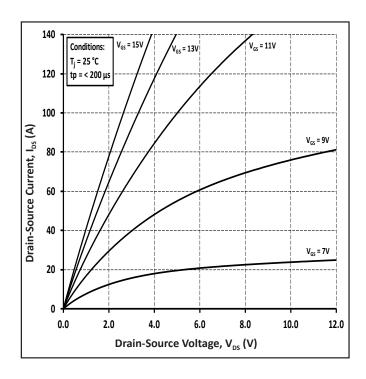


Figure 2. Output Characteristics T_J = 25 °C

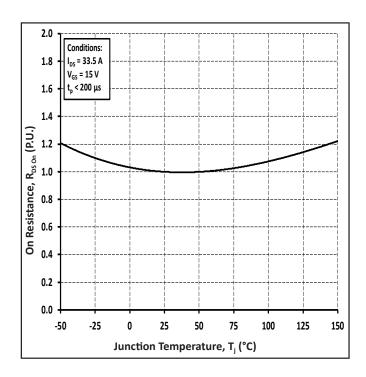


Figure 4. Normalized On-Resistance vs Temperature

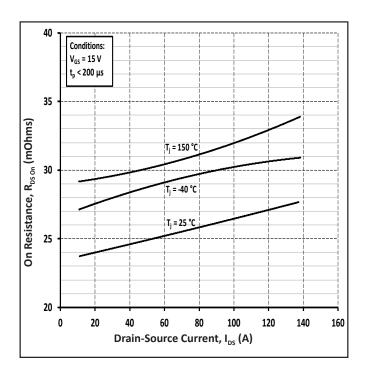


Figure 5. On-Resistance vs Drain Current for Various Temperatures

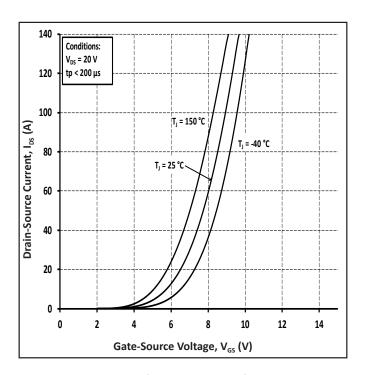


Figure 7. Transfer Characteristic for Various Junction Temperatures

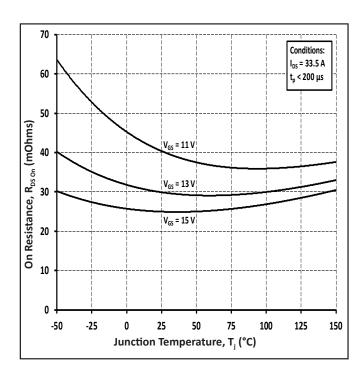


Figure 6. On-Resistance vs Temperature for Various Gate Voltage

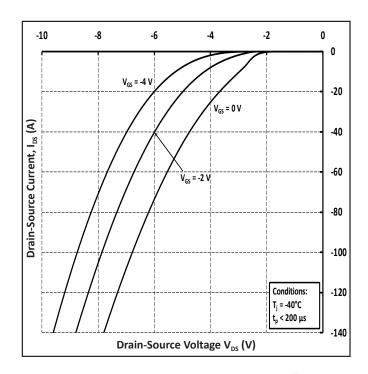


Figure 8. Body Diode Characteristic at -40 °C

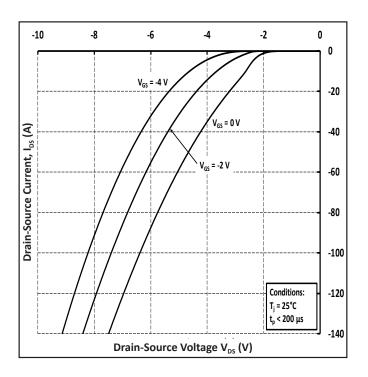


Figure 9. Body Diode Characteristic at 25 °C

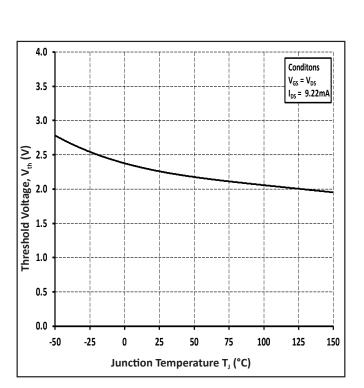


Figure 11. Threshold Voltage vs Temperature

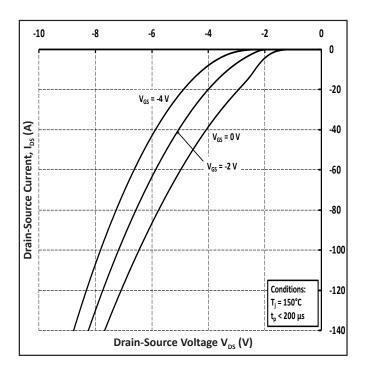


Figure 10. Body Diode Characteristic at 150 °C

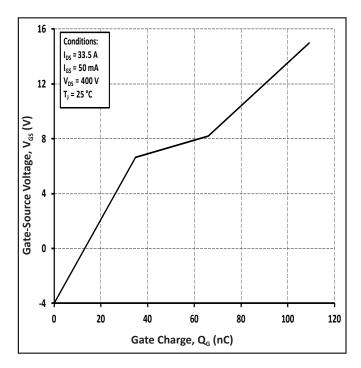


Figure 12. Gate Charge Characteristic

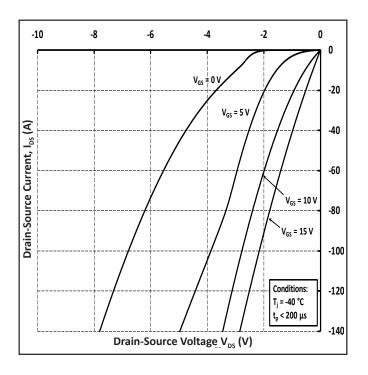


Figure 13. 3rd Quadrant Characteristic at -40 °C

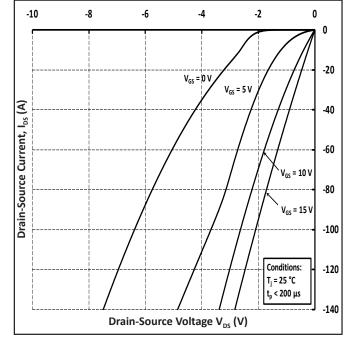


Figure 14. 3rd Quadrant Characteristic at 25 °C

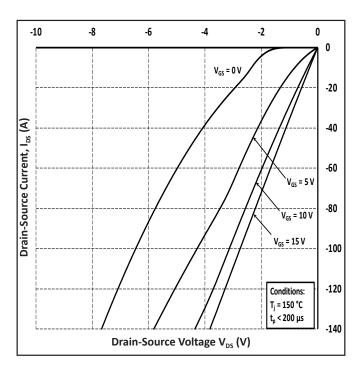


Figure 15. 3rd Quadrant Characteristic at 150 °C

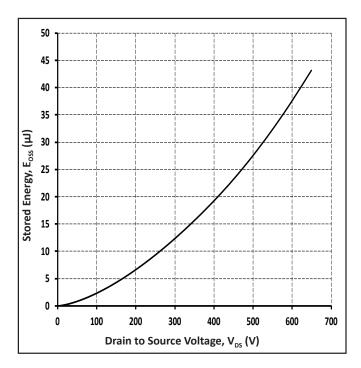


Figure 16. Output Capacitor Stored Energy

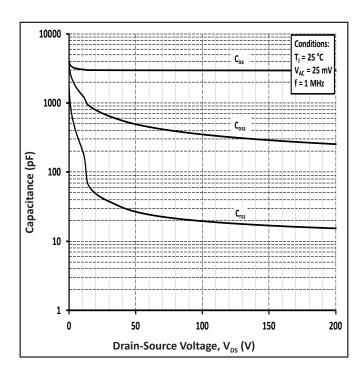


Figure 17. Capacitances vs Drain-Source Voltage (0-200 V)

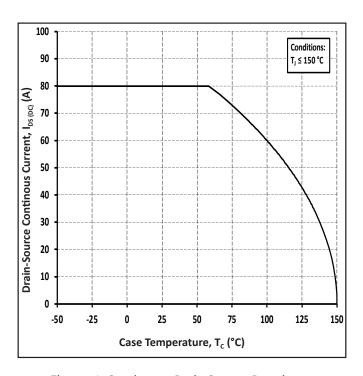


Figure 19. Continuous Drain Current Derating vs Case Temperature

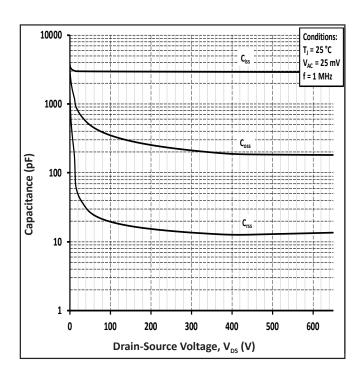


Figure 18. Capacitances vs Drain-Source Voltage (0-600 V)

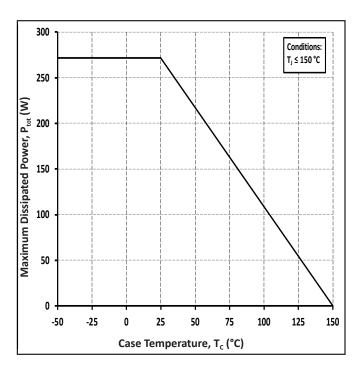


Figure 20. Maximum Power Dissipation Derating vs Case Temperature

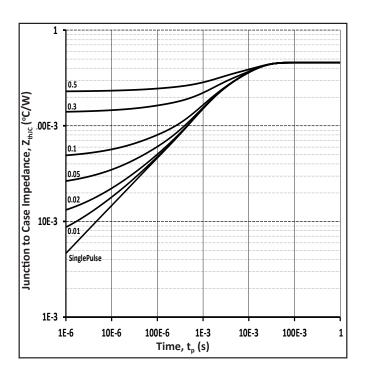


Figure 21. Transient Thermal Impedance (Junction - Case)

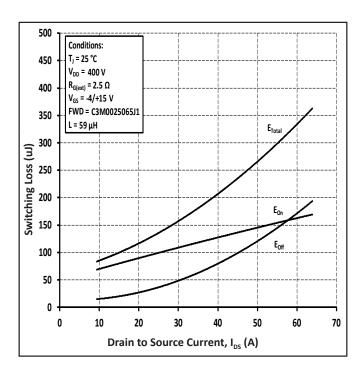


Figure 23. Clamped Inductive Switching Energy vs Drain Current (V_{DD} = 400 V)

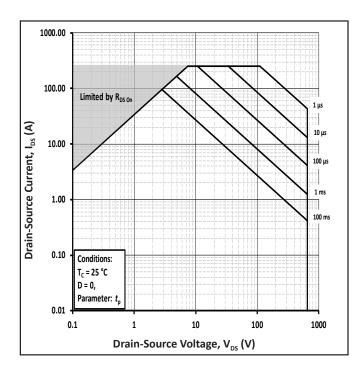


Figure 22. Safe Operating Area

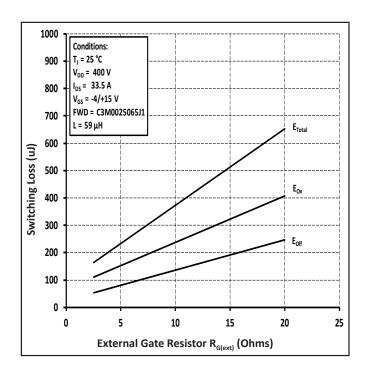


Figure 24. Clamped Inductive Switching Energy vs R_{G(ext)}

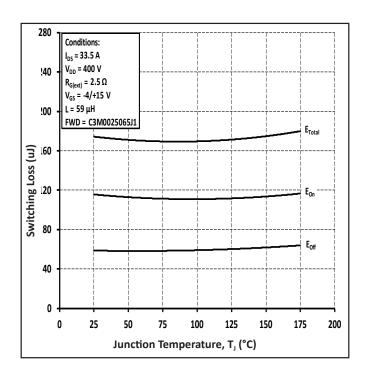


Figure 25. Clamped Inductive Switching Energy vs Temperature

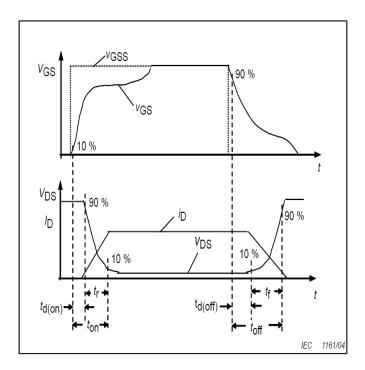


Figure 27. Switching Times Definition

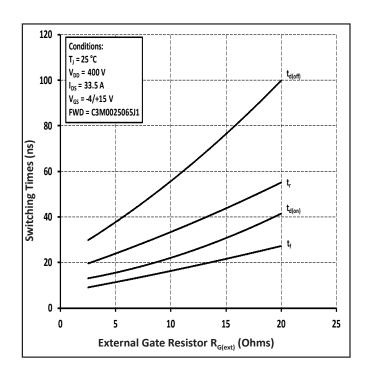


Figure 26. Switching Times vs $R_{\text{G(ext)}}$

Test Circuit Schematic

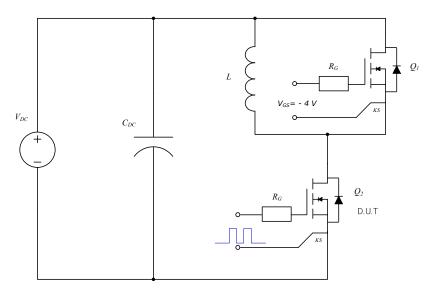
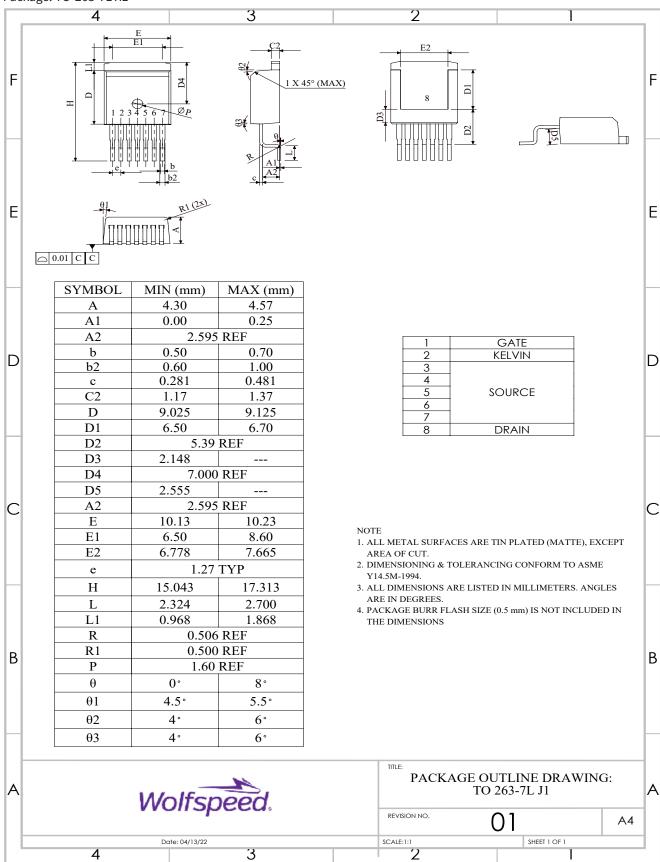


Figure 28. Clamped Inductive Switching Waveform Test Circuit

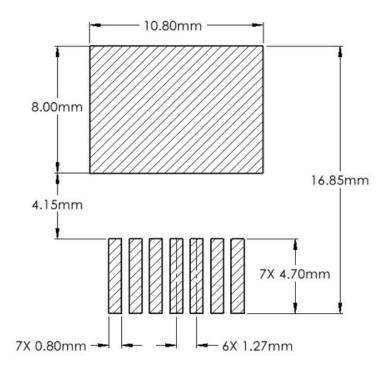
Note (4): Turn-off and Turn-on switching energy and timing values measured using SiC MOSFET Body Diode as shown above.

Package Dimensions

Package: TO-263-7L XL



Recommended Solder Pad Layout



Revision History

Current Revision	Date of Release	Description of Changes
0	October-2021	Initial Release
1	January-2024	Updated Wolfspeed branding, package drawing, package image, solder pad layout, added Rev history
2	December - 2024	Legal Disclaimer Updated

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Contact info:

4600 Silicon Drive Durham, NC 27703 USA Tel: +1.919.313.5300 www.wolfspeed.com/power

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